

L I M I T E D T E N D E R  
N O T I C E

Tender Ref. No. PUR-12/62/2021-MCAD\_DIV\_SAM\_CHE-SMR CHE DEPTT-12615 Date 22-10-2021 Tender Due Date 08-11-2021

To


Dear Sir,

The Purchase Officer, SAMEER-Centre for Electromagnetics invites sealed tender for the supply of materials / Services as per details given below:

Sl. No	Description of Items		Qty(Nos.)
1.	PCB Fabrication – 6 Layer board on Rogers substrate	(as per the specification enclosed)	5
2.	Components assembly		5

**Terms and Conditions:**

1. Tenders to be submitted to The Purchase Officer ,SAMEER-CEM ,CIT Campus,2<sup>nd</sup> Cross Road, Taramani, Chennai 600 113.
2. Delivery / Completion period should be clearly indicated.
3. Excise Duty, GST Percentage should be clearly indicated if admissible. Not eligible for FORM 'C' /'D'
4. WE ARE EXEMPTED FROM EXCISE DUTY
5. Quotation should be valid for atleast 60 days from the date of opening of the tender
6. Quotation should be sent in sealed envelope super scribing the tender reference number and tender due date. E-mail quotation will not be accepted. YOUR OFFER WILL NOT BE CONSIDERED IF OUR TENDER REFERENCE NO. & TENDER DUE DATE IS NOT MENTIONED ON COVER.
7. Late tenders will not be accepted under any circumstances
8. We reserve the right to accept or reject any quotations fully or partly without assigning any reasons.
9. For Further Clarification Please Contact 044-22544061 / 22544020 Email: [purchase.chn.sameer@nic.in](mailto:purchase.chn.sameer@nic.in)
10. Unsolicited bids shall not be considered

  
(P. Ramamoorthi)  
Head – Administration

Contd...,



CIT Campus, 2<sup>nd</sup> Cross Road, Taramani, Chennai - 600 113, India

सी.आई.टी.परीसर, दूसरा क्रॉस रोड, तारामणी चेन्नै - ६०० ११३.

दूरध्वनि : Tel : +91-44-22541583 / 1817 / 2106 / 2452 फैक्स / Fax : 2254 1838 / 1424

वेबसाइट : [www.sameer.org.in](http://www.sameer.org.in)

## SPECIFICATION LIST

SL No	REQUIREMENTS	VALUE
1	Board Name	mmBoard
2	Board Thickness	1.27 mm
3	Via Requirements	
	a.Through hole	Yes
	b.Blind via	Yes
	c.Buried via	NO
4	Via hole size / Pad size	
	a. Micro Via (Layer-1 to Layer-2)	0.127mm / 0.254mm, 240 Nos
	b. Via (Layer-1 to Layer-2)	350 Nos
	b. PTH Via	500 Nos
5	No. of Copper layers	6
6	Substrate Material(Top)	RO4350B, 10 mil
7	Preperg material	FR4, 8mil
8	Board Size	118mm x 39mm
9	Minimum Track Width, Gap	
	Top layer	3.2mil, 3.2mil (0.082mm)
	Bottom and inner layers	0.25mm, 0.15mm
10	Minimum gap	0.2mm
11	Board overall thickness tolerance	1.27mm +/- 10%
12	Solder mask	Top and bottom layer
13	Surface finish	ENIG
14	Copper thickness	17 microns
15	Solder mask color	no preference
16	Silk screen color	Top, White
17	ROHS compliance	required
18	Via on pad	No
19	Via filling	Yes
20	Edge plating	No
21	PCB type	Industrial grade
22	Fabrication file format	Gerber files RS-274X format
23	Impedance Control	Top Layer
24	Electrical testing	required
25	No of boards required	5
26	Fabrication lead time	25 days maximum

Thickness (mm)

Solder Mask	
Layer 1 – Copper	0.017
Substrate – RO4350B	0.254
Layer 2 – Copper	0.017
Prepreg – FR4	0.203
Layer 3 – Copper	0.017
Substrate – RO4350B	0.254
Layer 4 – Copper	0.017
Prepreg – FR4	0.203
Layer 5 – Copper	0.017
Substrate – RO4350B	0.254
Layer 6 – Copper	0.017
Solder Mask	
Total	1.27 mm

<b>S No</b>	<b>Components Assembly</b>	<b>Quantity</b>
1	Passives	
	Size- 0201	56
	Size- 0402	170
	Size- 0804	8
2	BGA – 0.5mm pitch – 49 pins	4
3	QFN – 24	1
4	PVQFN – 40	1
5	TSSOP – 14	4
6	SO-8	2
7	SOT-23	1
8	Connector – SMP	9
9	Connector – 32 Pin SMD 1.27mm pitch	1
10	Others	10